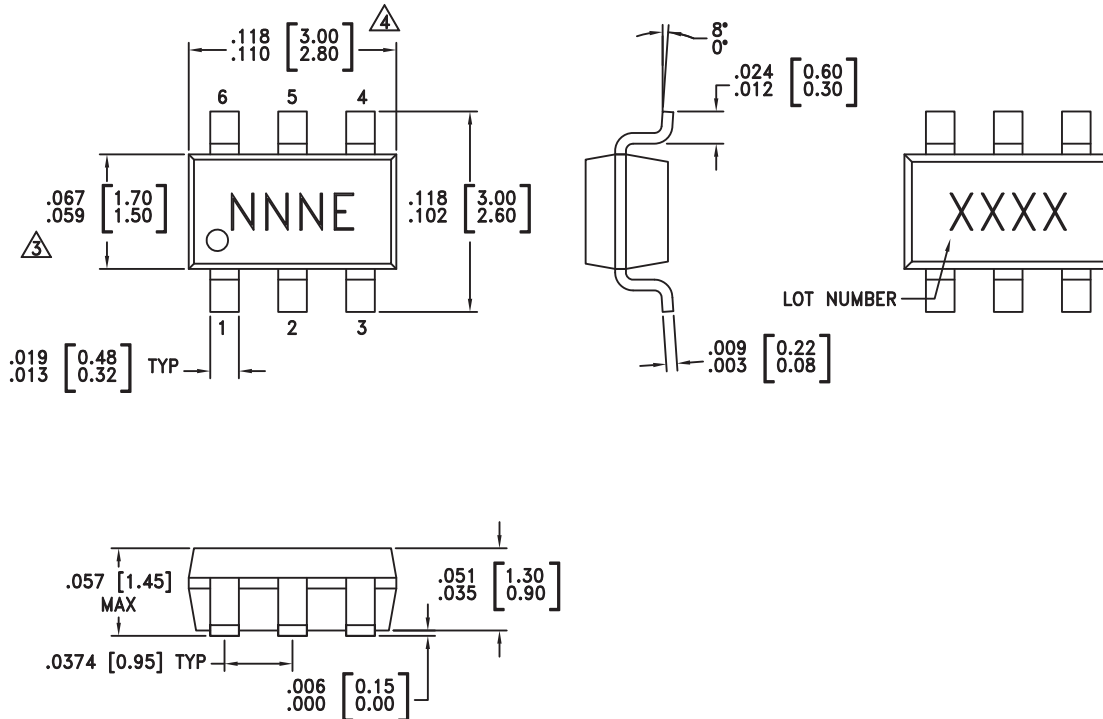


## SOT26 (E) – 6 LEAD PLASTIC SOT26 PACKAGE

### SOT26 (E) Package Outline Drawing



#### NOTES:

- LEADFRAME MATERIAL: COPPER ALLOY
- DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

### Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking <sup>[3][4]</sup>
	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 <sup>[1]</sup>	HNNN XXXX
E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 <sup>[2]</sup>	NNNE XXXX

[1] Max peak reflow temperature of 235 °C

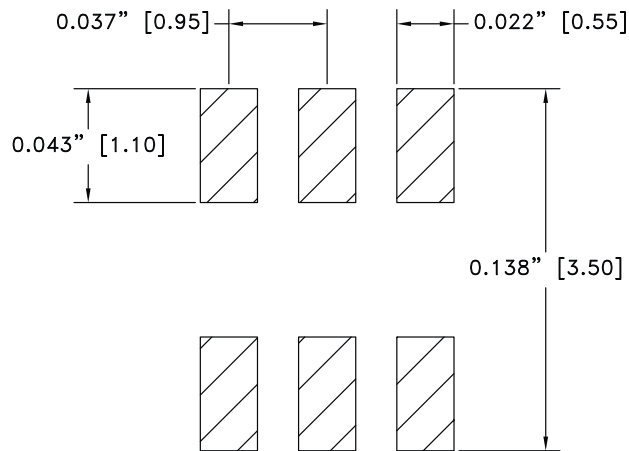
[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

[4] 3-Digit part number NNN

**SOT26 (E) – 6 LEAD PLASTIC  
SOT26 PACKAGE**

**Suggested SOT26 (E) PCB Land Pattern**



**NOTES:**

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.

